



4.72 2X

E2 (2X)

◆ 0.10**(M)** C A B 0.05**(M)** C

l→-(D3)

b (8X)

3 80 2X

1.42 4x

0.61

0.635

	O HAVE	NO TRA	CES OF	
DIM	MILLIMETERS			
	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
A1	0.00	-	0.05	
A3	0.23	0.28	0.33	
b	0.26	0.31	0.36	
b1	0.36	0.41	0.46	
D	5.00	5.10	5.20	
D1	4.80	4.90	5.00	
D2	1.51	1.61	1.71	
D3	0.54 REF			
E	6.20	6.30	6.40	
E1	5.70	5.80	5.90	
E2	3.58	3.68	3.78	
E3	0.30 REF			
E4	0.10	0.20	0.30	
E5	0.72 REF			
E6	0.59	0.69	0.79	
е	1.27 BSC			

3.81 BSC

0.635 BSC

1.19 REF 0.60 REF

0.45 REF

0.74

0.25

0.39 REF

0.84

0.35

0.64

0.15

0°

**DATE 23 APR 2021** 

*FOR ADDITIONAL INFORMATION ON OUR
PB-FREE STRATEGY AND SOLDERING
DETAILS, PLEASE DOWNLOAD THE ON
SEMICONDUCTOR SOLDERING AND
MOUNTING TECHNIQUES REFERENCE
MANUAL, SOLDERRM/D.

LAND PATTERN

RECOMMENDATION

1.27

KEEP OUT AREA

6.91

0.77

-1 27

e1

e/2

k1

k2

L2

z

θ

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(2X)

E6 (4X)

(k1)

D2

**BOTTOM VIEW**